

PATENT APPLICATION SERIAL NO. _____

U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICE
Fee Record Sheet

09/06/2001 55ITHIB1 00000022 192386 09944732

01 FC:101 710.00 CH
02 FC:102 160.00 CH
03 FC:103 90.00 CH

PTO-1556

(5/87)

08/31/01
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Docket No.: M-11443 US

August 31, 2000

Box Patent Application
Commissioner For Patents
Washington, D. C. 20231

Enclosed herewith for filing is a patent application, as follows:

Inventor(s): Smith, Lee John; Zoba, David Albert

Title: Thin Semiconductor Package Including Stacked Dies

X Return Receipt Postcard
X This Transmittal Letter (in duplicate)
24 page(s) Specification(not including claims)
8 page(s) Claims
1 page Abstract
6 Sheet(s) of Drawings (Figs. 1, 2, 3, 3a, 4, 4a, 5, 6, 7, 8, and 9)
2 page(s) Declaration For Patent Application and Power of Attorney
1 page NonPublication Request
1 page(s) Recordation Form Cover Sheet (in duplicate)
2 ✓ page(s) Assignment

CLAIMS AS FILED

For	Number Filed	Number Extra	Rate	Basic Fee
Total Claims	25	-20 = 5	x \$ 18.00	\$ 710.00
				\$ 90.00
Independent Claims	5	-3 = 2	x \$80	\$ 160.00
<input type="checkbox"/> Fee of _____ for the first filing of one or more multiple dependent claims per application \$				
<input type="checkbox"/> Fee for Request for Extension of Time \$				

Please make the following charges to Deposit Account 19-2386:

Total fee for filing the patent application in the amount of \$ 960.00
 The Commissioner is hereby authorized to charge any additional fees which may be
required, or credit any overpayment to Deposit Account 19-2386.

EXPRESS MAIL LABEL NO:

EL 873 332 249 US

Respectfully submitted,

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09/944732
08/31/01

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MODIFIED PTO/SB/35 (11-00)

REQUEST AND CERTIFICATION UNDER 35 U.S.C. 122(b)(2)(B)(i)	Inventors	Smith, Lee John; Zoba, David Albert
	Title	Thin Semiconductor Package Including Stacked Dies
	Atty Docket Number	M-11443 US

I hereby certify that the invention disclosed in the attached application **has not and will not be** the subject of an application filed in another country, or under a multilateral agreement, that requires publication at eighteen months after filing. I hereby request that the attached application not be published under 35 U.S.C. 122(b).

August 31, 2001
Date



Robert D. Wasson
Attorney for Applicants
Reg. No.: 40,218

This request must be signed in compliance with 37 CFR 1.33(b) and submitted with the application **upon filing**.

Applicant may rescind this nonpublication request at any time. If applicant rescinds a request that an application not be published under 35 U.S.C. 122(b), the application will be scheduled for publication at eighteen months from the earliest claimed filing date for which a benefit is claimed.

If applicant subsequently files an application directed to the invention disclosed in the attached application in another country, or under a multilateral international agreement, that requires publication of applications eighteen months after filing, the applicant **must** notify the United States Patent and Trademark Office of such filing within forty-five (45) days after the date of the filing of such foreign or international application. **Failure to do so will result in abandonment of this application (35 U.S.C. 122(b)(2)(B)(iii)).**

7 CFR 1.213(a) provides for a request that an application not be published under 35 U.S.C. 122(b). Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.14. SEND TO: Commissioner for Patents, Washington, DC 20231.